



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant(s): Oleg Siniaguine  
Assignee: Tru-Si Technologies, Inc.  
Title: Semiconductor Structures Having Multiple Conductive Layers In An Opening, And Methods For Fabricating Same  
Application No.: 09/941,447 Filing Date: August 28, 2001  
Examiner: Thomas, Toniae M. Group Art Unit: 2822  
Docket No.: M-9999-1D US

San Jose, California  
September 10, 2003

Director of USPTO  
P.O. Box 1450  
Alexandria, VA 22313-1450

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**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97(C) WITH  
CERTIFICATION UNDER 37 C.F.R. § 1.97(E)(1)**

Dear Sir:

Pursuant to 37 C.F.R. § § 1.56, 1.97 and 1.98, Applicants wish to call the documents listed on the enclosed Form PTO-1449 (1 page) to the Examiner's attention for the above-identified patent application. Copies of the listed documents are enclosed. The documents were first cited by the European Patent Office in a corresponding PCT Application No. PCT/US 02/05371. The relevance of any foreign language documents is explained in the accompanying English abstracts and the enclosed PCT International Search Report.

Citation of the above documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or

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3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

The undersigned hereby certifies in accordance with § 1.97(e)(1) that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

**Statement under 37 C.F.R. §1.704(d)**

Each item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart application and this communication was not received by any individual designated in §1.56(c) more than thirty days prior to the filing of the information disclosure statement.

Please charge the amount of \$180.00 to deposit account 50-2257. Also, please charge any additional fees required and credit any overpayment to our Deposit Account No. 50-2257. This form is being submitted in duplicate.

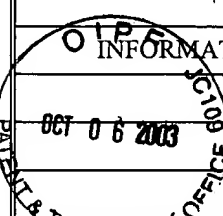
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Director of USPTO, P.O. Box 1450, Alexandria, VA 22313-1450, on September 30, 2003.

*Michael Shenker* 9-30-03  
Attorney for Applicant(s)      Date of Signature

Respectfully submitted,

*Michael Shenker*

Michael Shenker  
Attorney for Applicant(s)  
Reg. No. 34,250

U.S. Department of Commerce, Patent and Trademark Office		Atty Docket No.	Serial No.
		M-9999-1D US	09/941,447
		Applicant(s)	
		Oleg Siniaguine	
		Filing Date	Group
		August 28, 2001	2822

## U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,229,647	20 Jul 1993	Gnadinger			
	AB	5,270,261	14 Dec. 1993	Bertin et al.			
	AC	5,528,080	18 Jun. 1996	Goldstein			
	AD	6,002,177	14 Dec. 1999	Gaynes et al.			
	AE	6,104,043	15 Aug. 2000	Hermansson et al			
	AF	6,122,187	19 Sep. 2000	Ahn et al.			
	AG	6,184,060	6 Feb. 2001	Siniaguine			
	AH						
	AI						
	AJ						
	AK						

## Foreign Patent Documents

							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AQ	
	AR	
	AS	

Examiner

Date Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.